



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

*: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-04-06
Contact Name *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Authorized Representative *	Giovanni Giacobello
Authorized Representative *	Giovanni Giacobello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		


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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STF18NM80	XAFP*M28LB52	A	3068	2018-04-06
Amount	UoM	Unit type	ST ECOPACK Grade	
1900	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-16.15-4.5	3	Through-hole	
Comment	TO 220 ISO FULL PACK IN LINE			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 15th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.83	Die - Leadframe	436
Lead	19.65	Soft solder	10344

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	XSPF*M28L852				6000000.0	1000000.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	23.417	mg	supplier	die	Silicon (Si)	7440-21-3		22.503	mg	960969	11844
				supplier	metallization	Aluminium (Al)	7429-90-5		0.438	mg	18704	231
				supplier	Passivation	Silicon Nitride	12033-89-5		0.106	mg	4527	56
				supplier	Passivation	Silicon Oxide	7631-86-9		0.151	mg	6448	79
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.011	mg	470	6
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.154	mg	6576	81
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.054	mg	2306	28
Leadframe	M-004 Copper and its alloys	605.984	mg	supplier	alloy	Copper (Cu)	7440-50-8		604.468	mg	997498	318141
				supplier	alloy	Iron (Fe)	7439-89-6		0.605	mg	999	318
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.182	mg	300	96
				supplier	metallization	Nickel (Ni)	7440-02-0		0.674	mg	1112	355
				supplier	metallization	Phosphorus (P)	7723-14-0		0.055	mg	91	29
Soft solder	Solder	20.580	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	19.653	mg	954956	10344
				supplier	solder	Silver (Ag)	7440-22-4		0.515	mg	25024	271
				supplier	solder	Tin (Sn)	7440-31-5		0.412	mg	20020	217
Bonding wires	M-011 Other inorganic materials	1.084	mg	supplier	wire	Aluminium (Al)	7429-90-5		1.080	mg	996310	568
				supplier	wire	Magnesium (Mg)	7439-95-4		0.004	mg	3690	2
				supplier								
Encapsulation	M-011 Other inorganic materials	1243.069	mg	supplier	mold compound	Quartz	14808-60-7		870.148	mg	700000	457973
				supplier	mold compound	Silica, vitreous	60676-86-0		93.230	mg	75000	49068
				supplier	mold compound	Epoxy resin	25068-38-6		174.030	mg	140000	91595
				supplier	mold compound	phenol resin	29690-82-2		87.015	mg	70000	45797
				supplier	mold compound	metal hydroxide	21645-51-2		12.431	mg	10000	6543
				supplier	mold compound	carbon black	1333-86-4		6.215	mg	5000	3271
Connections coating	Solder	5.866	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.866	mg	1000000	3087